

Title (en)

LAYING DEVICE, CONTACTING DEVICE, ADVANCING SYSTEM, LAYING AND CONTACTING UNIT, PRODUCTION SYSTEM, METHOD FOR THE PRODUCTION AND A TRANSPONDER UNIT

Title (de)

VERLEGEVORRICHTUNG, KONTAKTIERVORRICHTUNG, ZUSTELLSYSTEM, VERLEGE- UND KONTAKTIEREINHEIT  
HERSTELLUNGSANLAGE, VERFAHREN ZUR HERSTELLUNG UND EINE TRANSPONDEREINHEIT

Title (fr)

DISPOSITIF DE POSE, DISPOSITIF D'ETABLISSEMENT DE CONTACT, SYSTEME D'AVANCE, UNITE DE POSE ET D'ETABLISSEMENT DE CONTACT, INSTALLATION DE PRODUCTION, PROCEDE DE PRODUCTION ET ENSEMBLE TRANSPONDEUR

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2006050691A2] The invention relates to a laying device which is used to lay wire windings on transponder units, wherein the wire is guided in an axial manner in the laying device, a contacting device is used place the wires in contact with an automatic thermal clamping arrangement, an advancing system is used to advance machining devices by means of a piezo-leg-motor, a production system is used to produce transponder units in a console structural manner. The invention also relates to a method for the production of transponder units with horizontal ultrasonic introduction and a transponder unit wherein the wire ends engage directly on the ends of the connection surfaces of the chip.

IPC 8 full level

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DOCDB simple family (application)

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